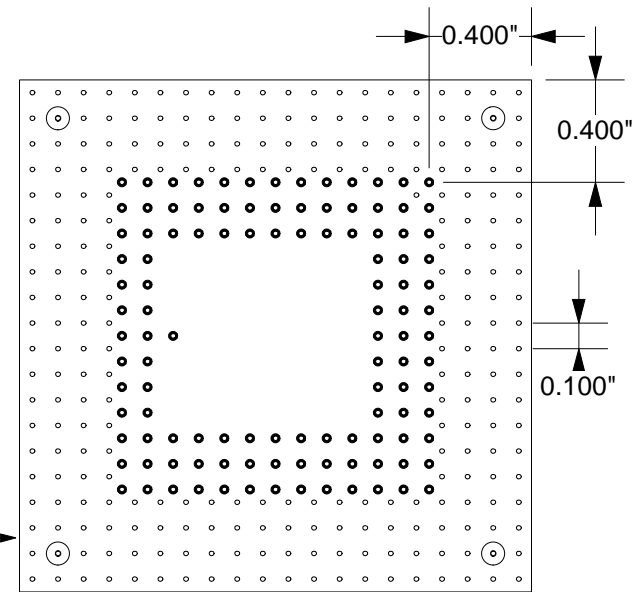
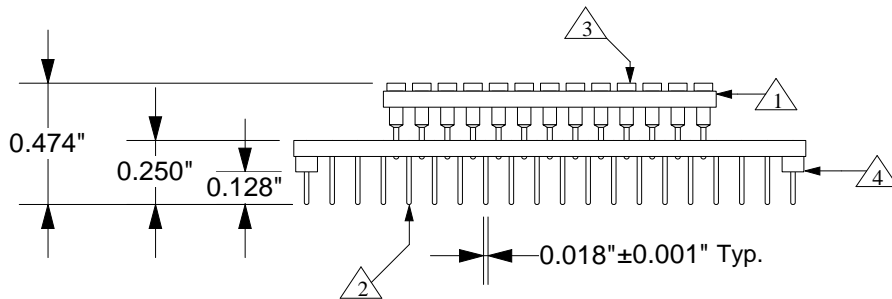


Top View




Bottom View



Side View

- 1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- 2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- 3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)
- 4 Stand-off: material- Teflon; 0.085" Dia; 0.060" thick.

Description: Device Convertor
 114 position PGA socket pattern (0.100" centers, 13x13 array, Motorola 68HC08PZ120) to
 257 Position PGA terminal pins (0.100" centers, 20x20 array, Motorola 68HC908LZ120).

DC-PGA/PGA-68HC08-01 Drawing		Status: Released	Scale 2:1	Rev: A
 <p>© 1999 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: M Gilk		Date: 3/10/99	
	File: DC-PGA/PGA-68HC08-01 Dwg		Modified:	

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.